

Bill of Materials

TI DESIGNS

TIPD160: Digitally Tunable MDAC based State Variable Filter

Item #	Quantity	Value	Designator	Description	Manufacturer	PartNumber
1	14	1uF	C1, C2, C9, C10, C11, C12, C15, C17, C18, C20, C25, C26, C28, C30	CAP, CERM, 0.1uF, 25V, +/-10%, X5R, 0603	MuRata	GRM188R61E104KA01D
2	11	100pF	C3, C4, C7, C8, C13, C14, C16, C21, C22, C24, C31	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	TDK	C1608C0G1H101J
3	1		C5	Not Installed	MuRata	
4	2	1000pF	C6, C23	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	MuRata	GRM188R71H102KA01D
5	3	10uF	C19, C27, C29	CAP, CERM, 10uF, 25V, +/-10%, X5R, 1206	MuRata	GRM31CR61E106KA12L
6	4		J1, J3, J4, JP8	Header, 100mil, 2x1, Gold, TH	Samtec	TSW-102-07-G-S
7	4		J2, J5, J6, J9	Connector, TH, SMA	Emerson Network Power	142-0701-201
8	1		J7	Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	On-Shore Technology	ED555/2DS
9	1		J8	Terminal Block, 6A, 3.5mm Pitch, 3-Pos, TH	On-Shore Technology	ED555/3DS
10	9		JP1, JP2, JP3, JP4, JP5, JP6, JP7, JP9, JP10	Header, TH, 100mil, 3x1, Gold plated, 230 mil above insulator	Samtec	TSW-103-07-G-S
11	1	49.9kΩ	R1	RES, 49.9 ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-0749R9L
12	4		TP1, TP6, TP10, TP12	Test Point, Miniature, Black, TH	Keystone	5001
13	8		TP2, TP3, TP4, TP5, TP7, TP8, TP9, TP11	Test Point, Miniature, Red, TH	Keystone	5000
14	3		U1, U2, U4	Dual, Serial Input 16-Bit Multiplying Digital-to-Analog Converter, PW0016A	Texas Instruments	DAC8812ICPW
15	4		U3, U5, U6, U7	High Precision OPERATIONAL AMPLIFIER, D0008A	Texas Instruments	OPA277U

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